

ABSTRACT

The invention is to form plated films on a conductive foil at high precision, and simplify a procedure of forming the plated film. A resin film composed of a thermosetting resin is formed on the surface of the conductive foil. The resin film of parts which become bonding pads and die pads is eliminated by a laser etching. A clamper presses of the periphery of the block so as to form hermetically sealed spaces on the block. The interior of the clamper is filled with a plating liquid by means of an injection means and an evacuation means, and subsequently, and Ag plated film is formed by an electroplating method.